

DZ2633000L

Zener Diode DZ2633000L

Unit : mm

Silicon epitaxial planar type For constant voltage / For surge absorption circuit DZ27330 in ML2 type package

- Excellent rising characteristics of zener current IZ
- Low zener operating resistance RZ
- Halogen-free / RoHS compliant

(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol : HG

Packaging

Embossed type (Thermo-compression sealing) : 10 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

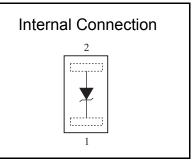
Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation *1	PT	100	mW
Electrostatic discharge ^{*2}	ESD	±8	kV
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1 PT = 100 mW achieved with a printed circuit board.

*2 Test method:IEC61000_4_2

(C = 150 pF , R = 330 Ω , Contact discharge : 10 times)

0.6



Electrical Characteristics Ta = $25 \circ C \pm 3 \circ C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 2 mA	31.35		34.65	V
Zener operating resistance	RZ	IZ = 2 mA			200	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			200	Ω
Reverse current	IR	VR = 25 V			0.05	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 2 mA		32.0		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25 $^\circ C$ for VZ mesurement.

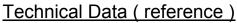
VZ value measured at other temperature must be adjusted to VZ (25 $^\circ$ C)

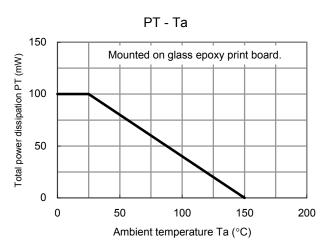
*2 VZ guaranteed 20 ms after current flow.

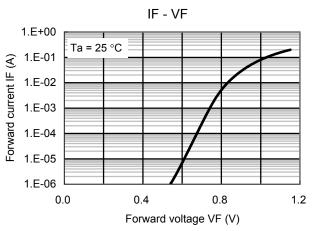
*3 Tj = 25 °C to 150 °C

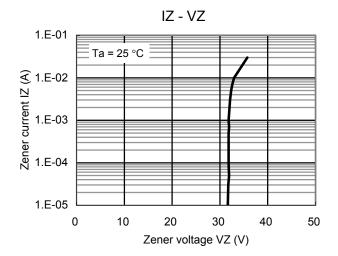
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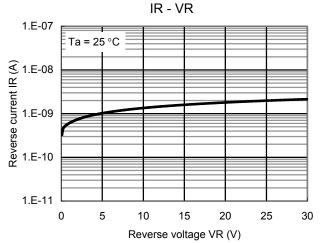
Panasonic

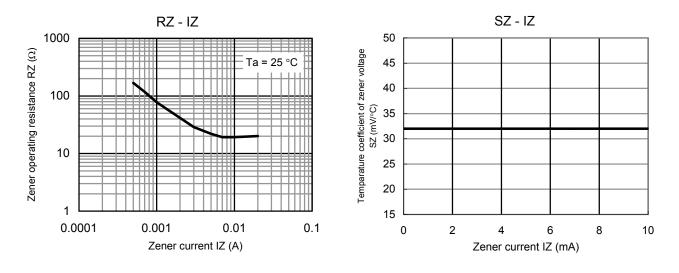












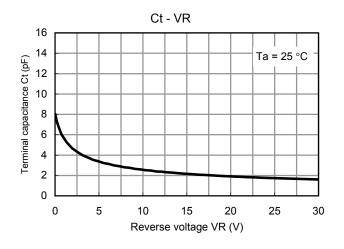
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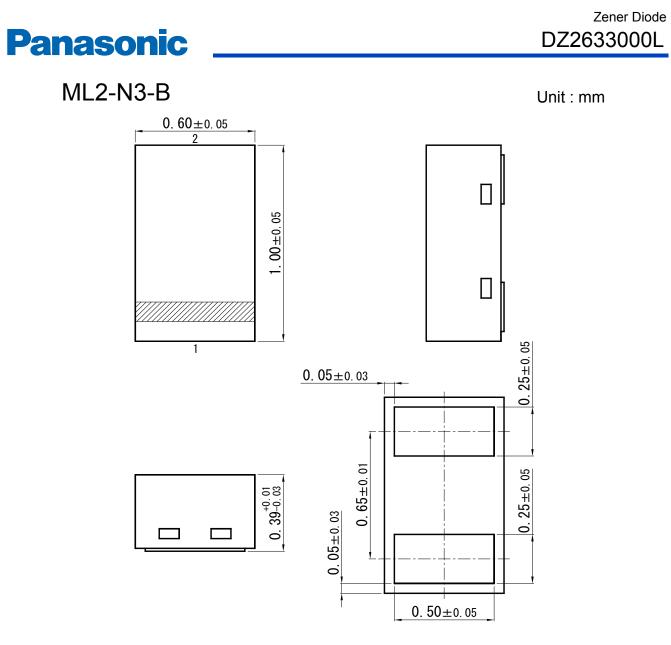
Established : 2013-04-20 Revised : ###-##-## Doc No. TT4-EA-14645 Revision. 1



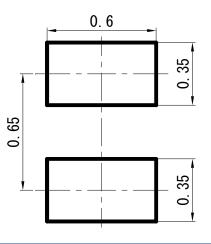
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Technical Data (reference)





■ Land Pattern (Reference) (Unit : mm)



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Established : 2013-04-20 Revised : ###-##-##

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